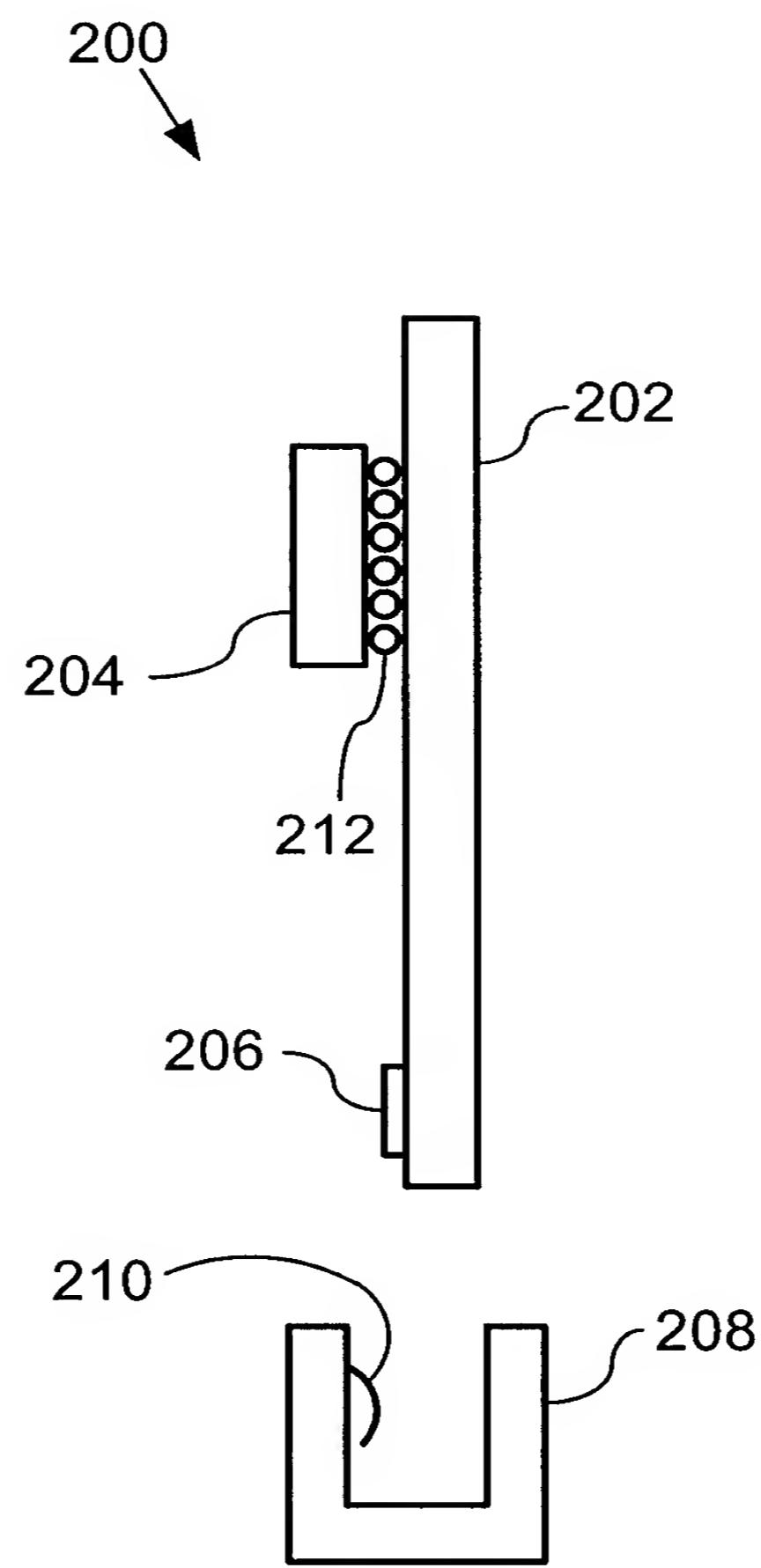
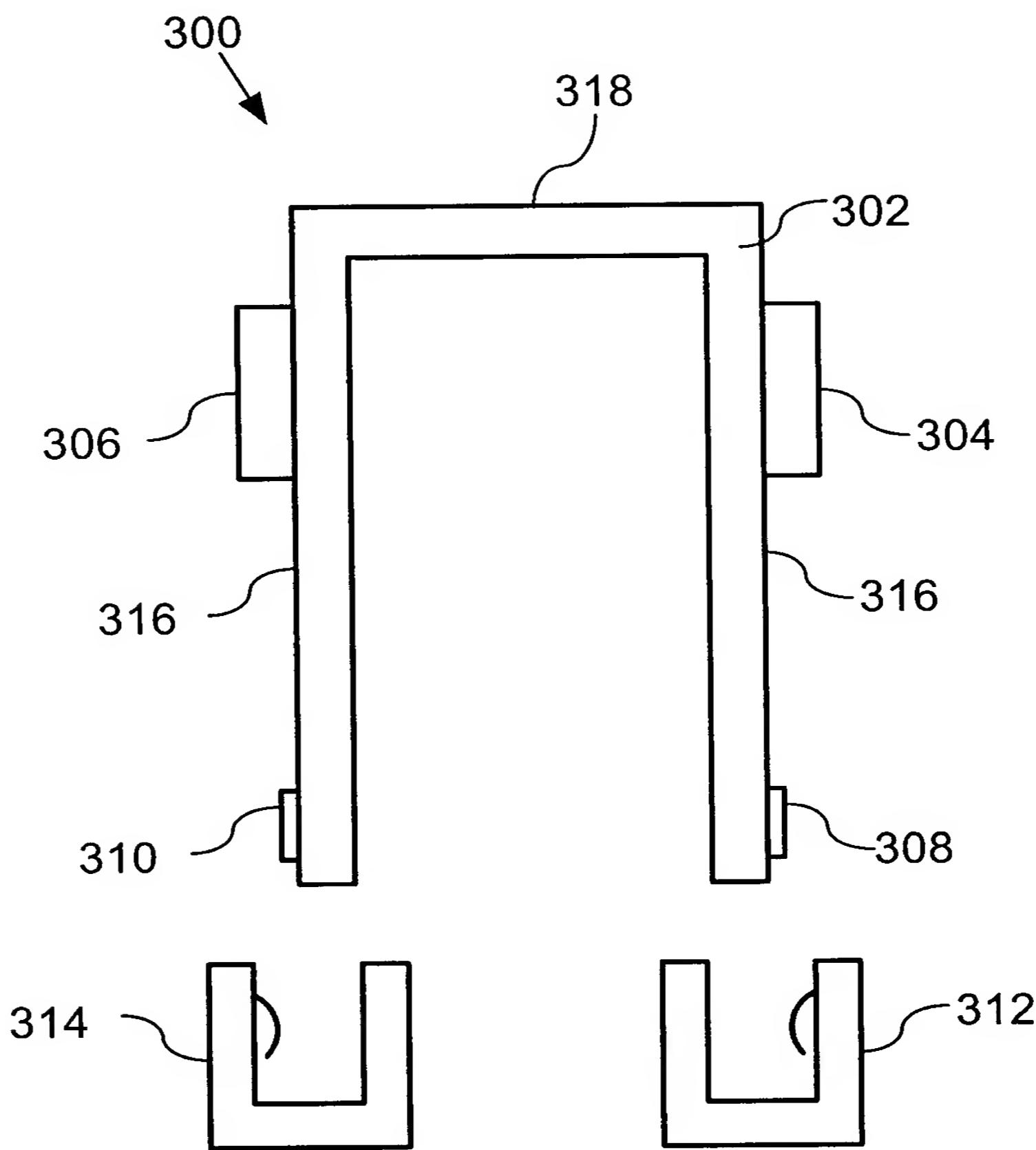
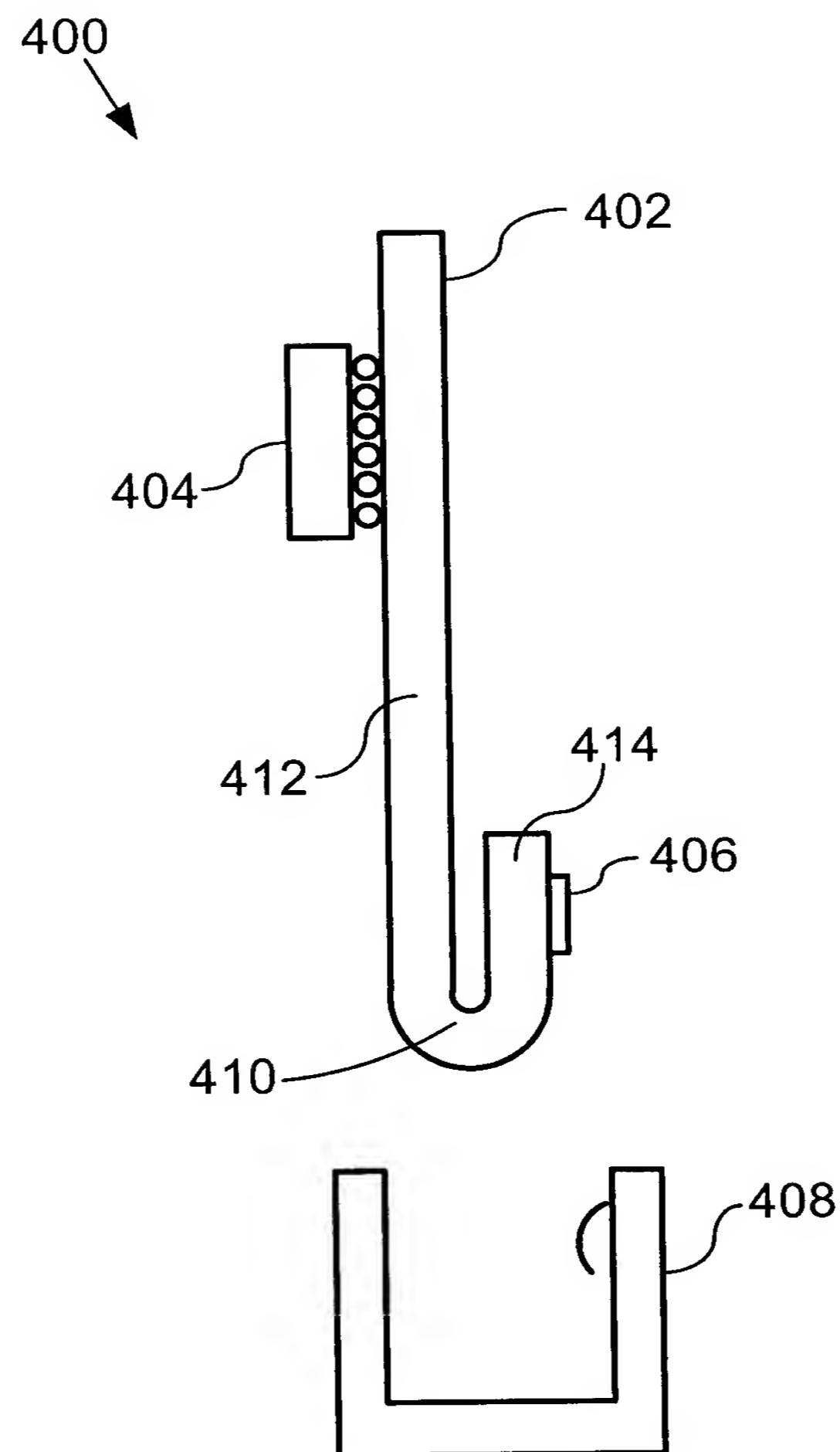


FIG. 1

SEARCHED SERIALIZED INDEXED FILED **FIG. 2**

**FIG. 3**

**FIG. 4**

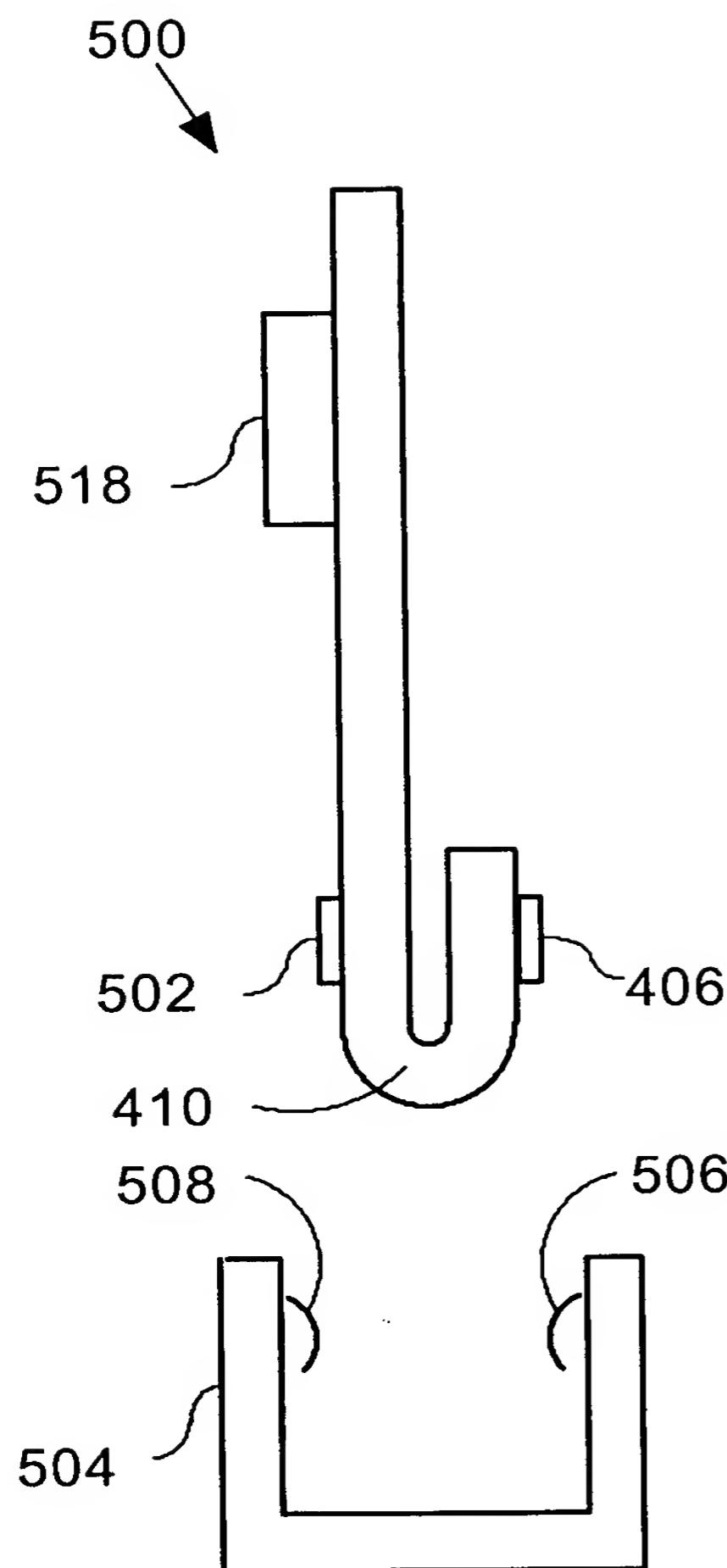


FIG. 5A

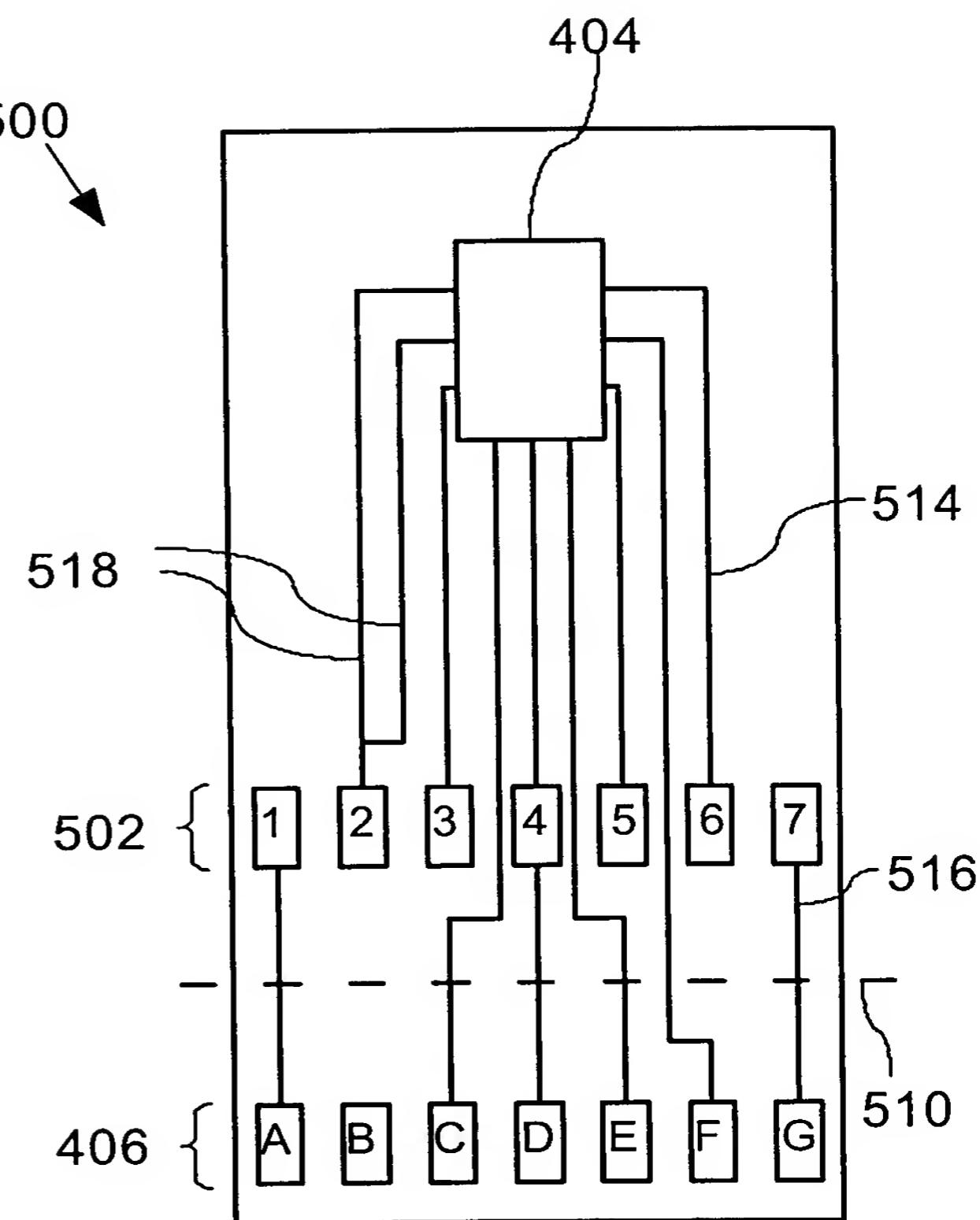


FIG. 5B

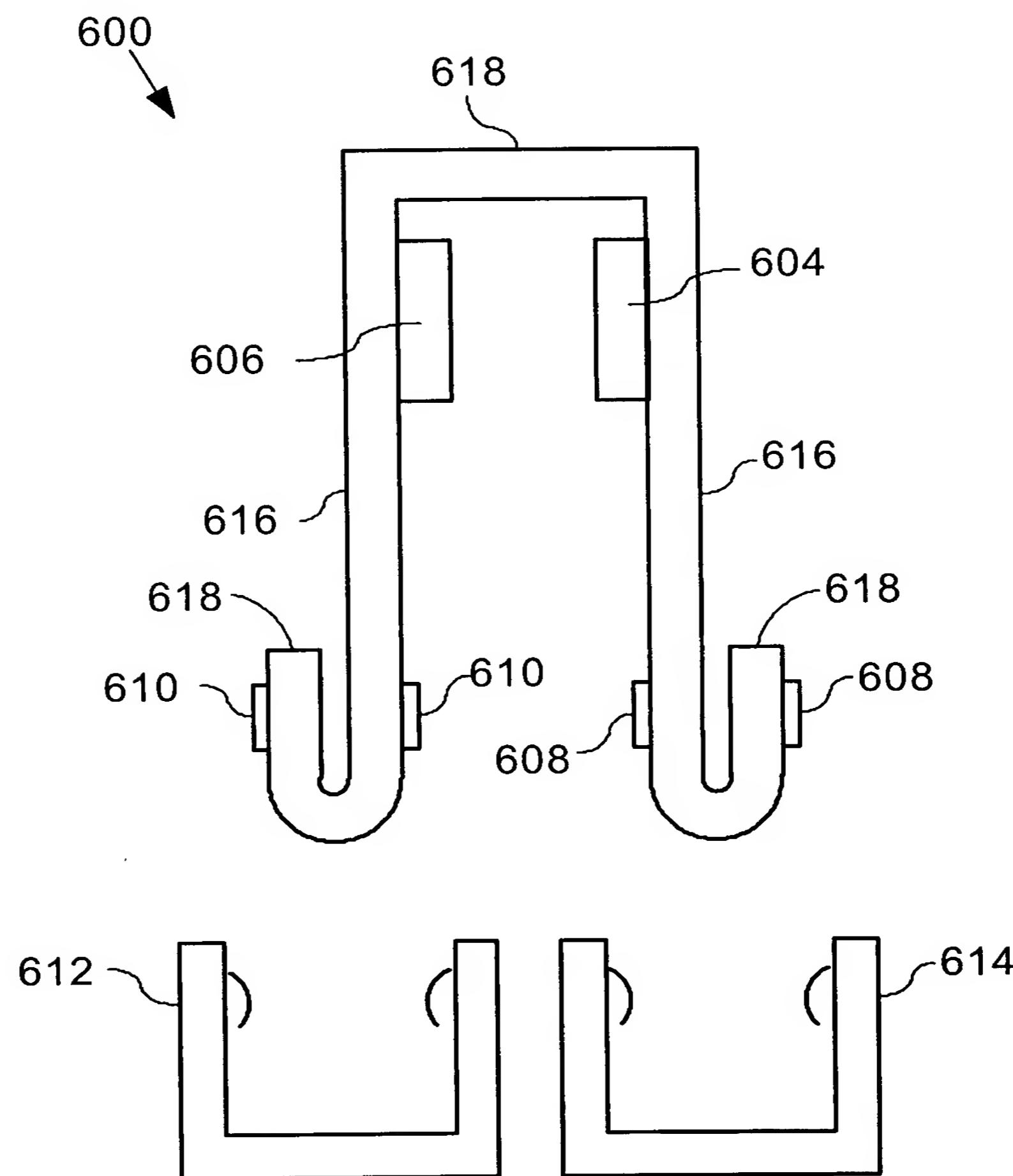


FIG. 6

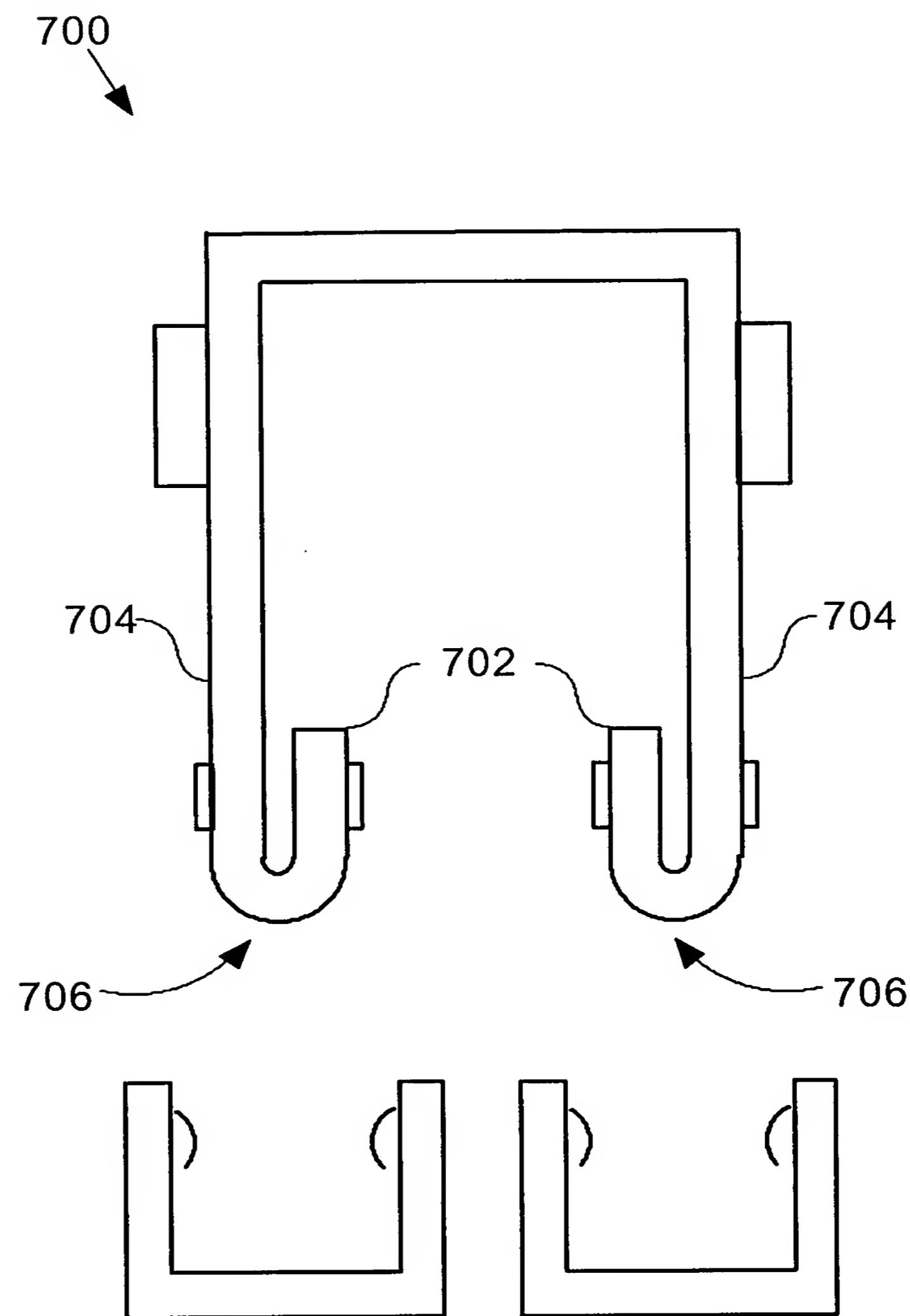


FIG. 7

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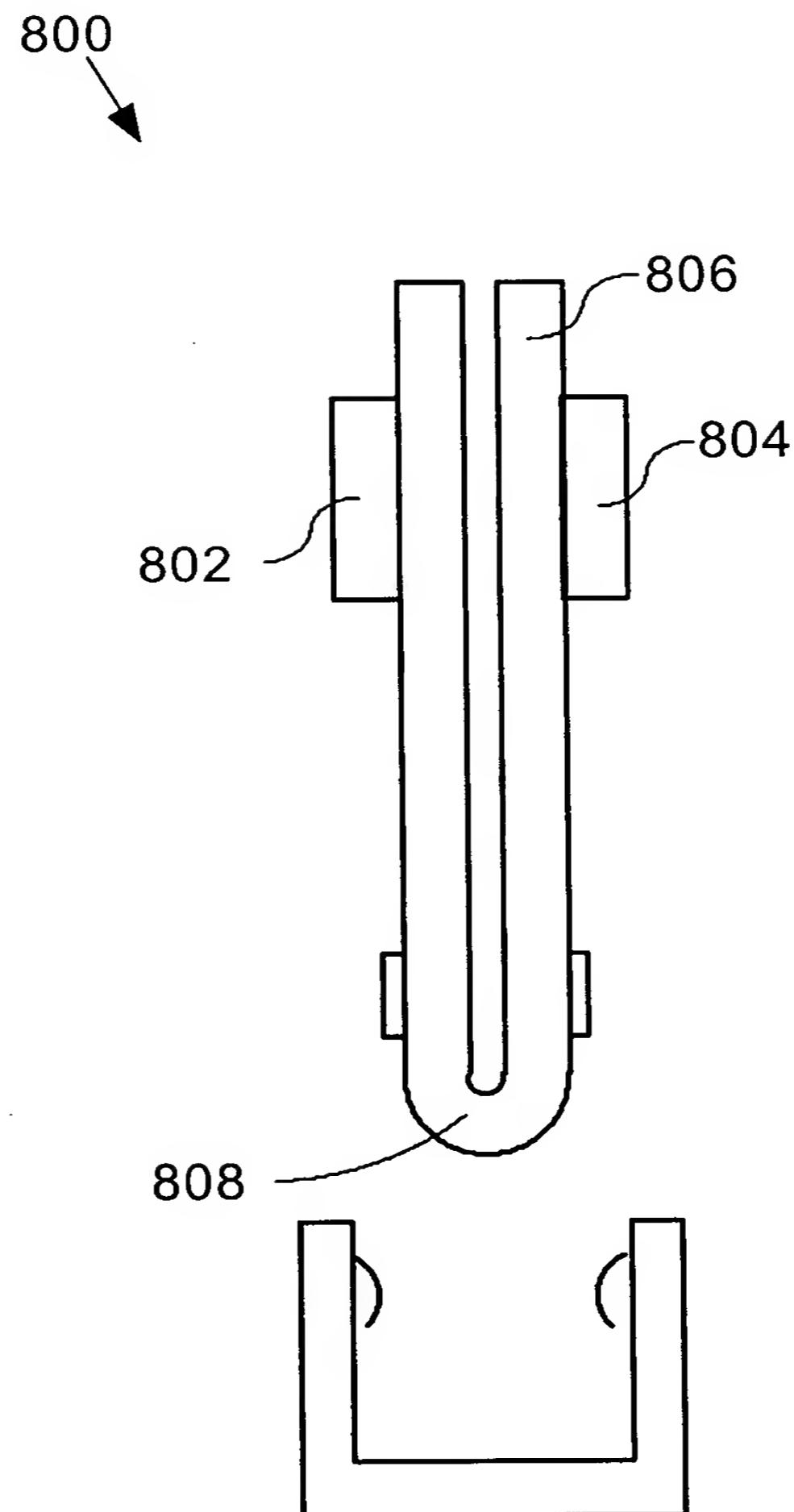


FIG. 8

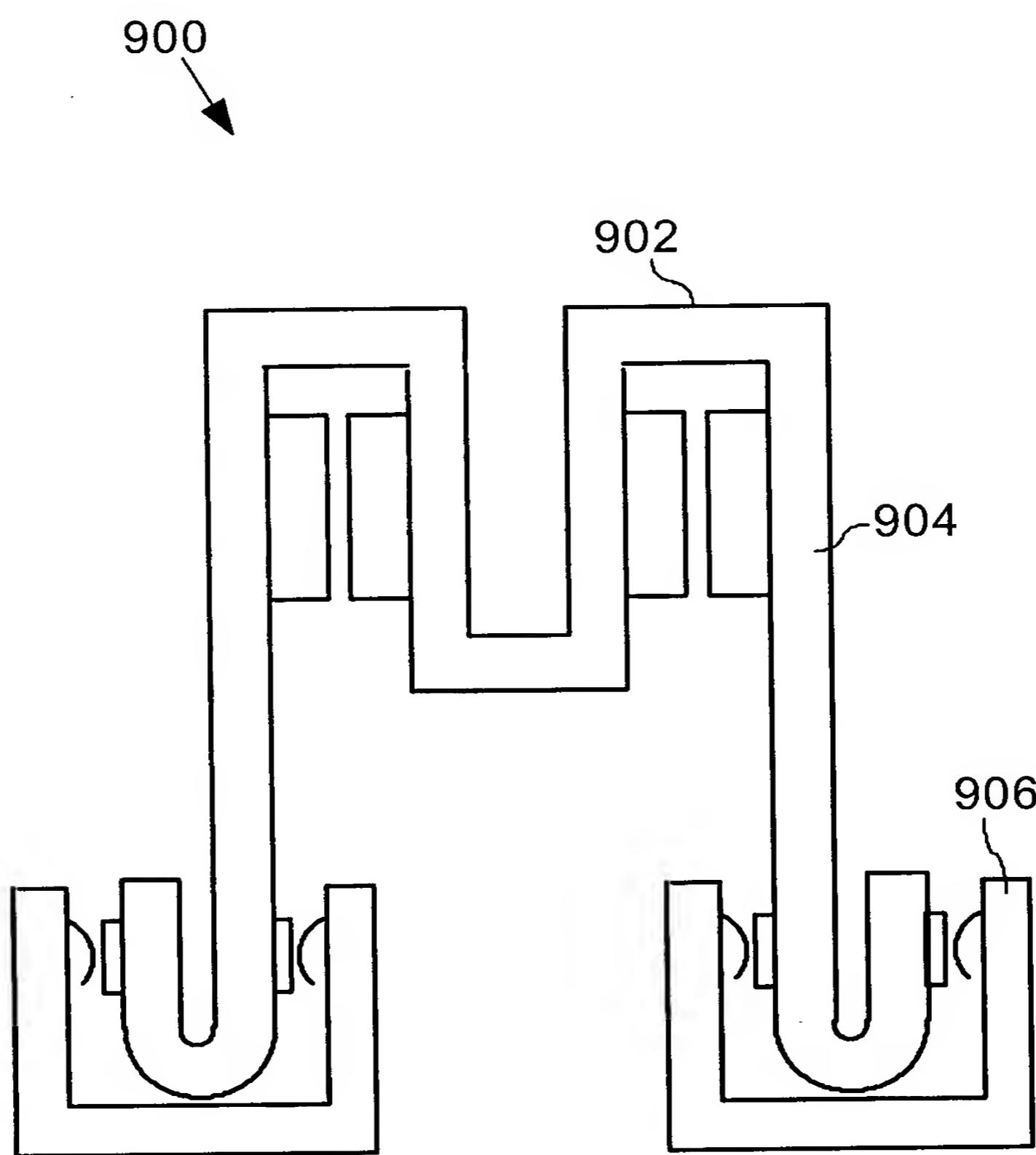


FIG. 9

10/12

+

1000

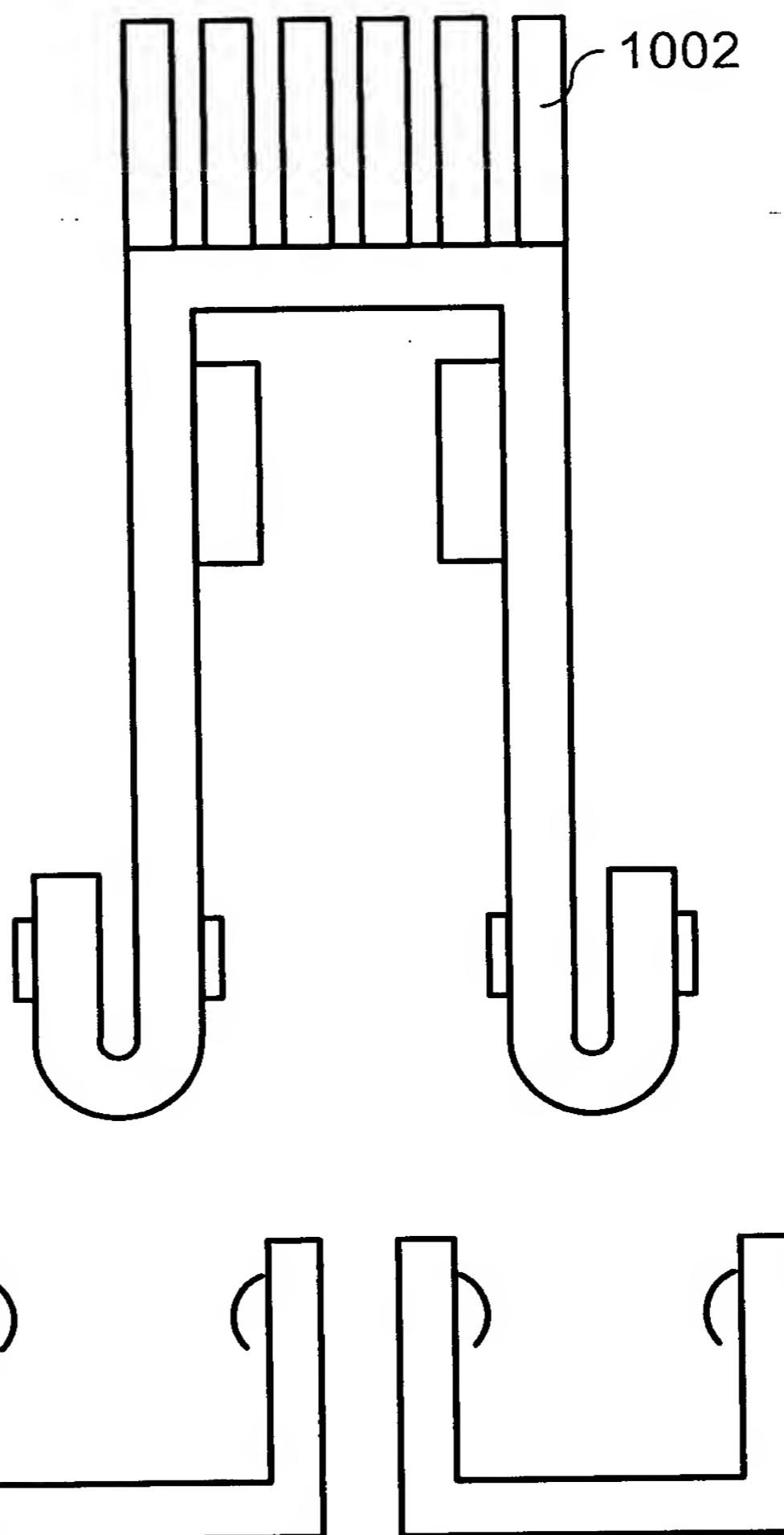


FIG. 10

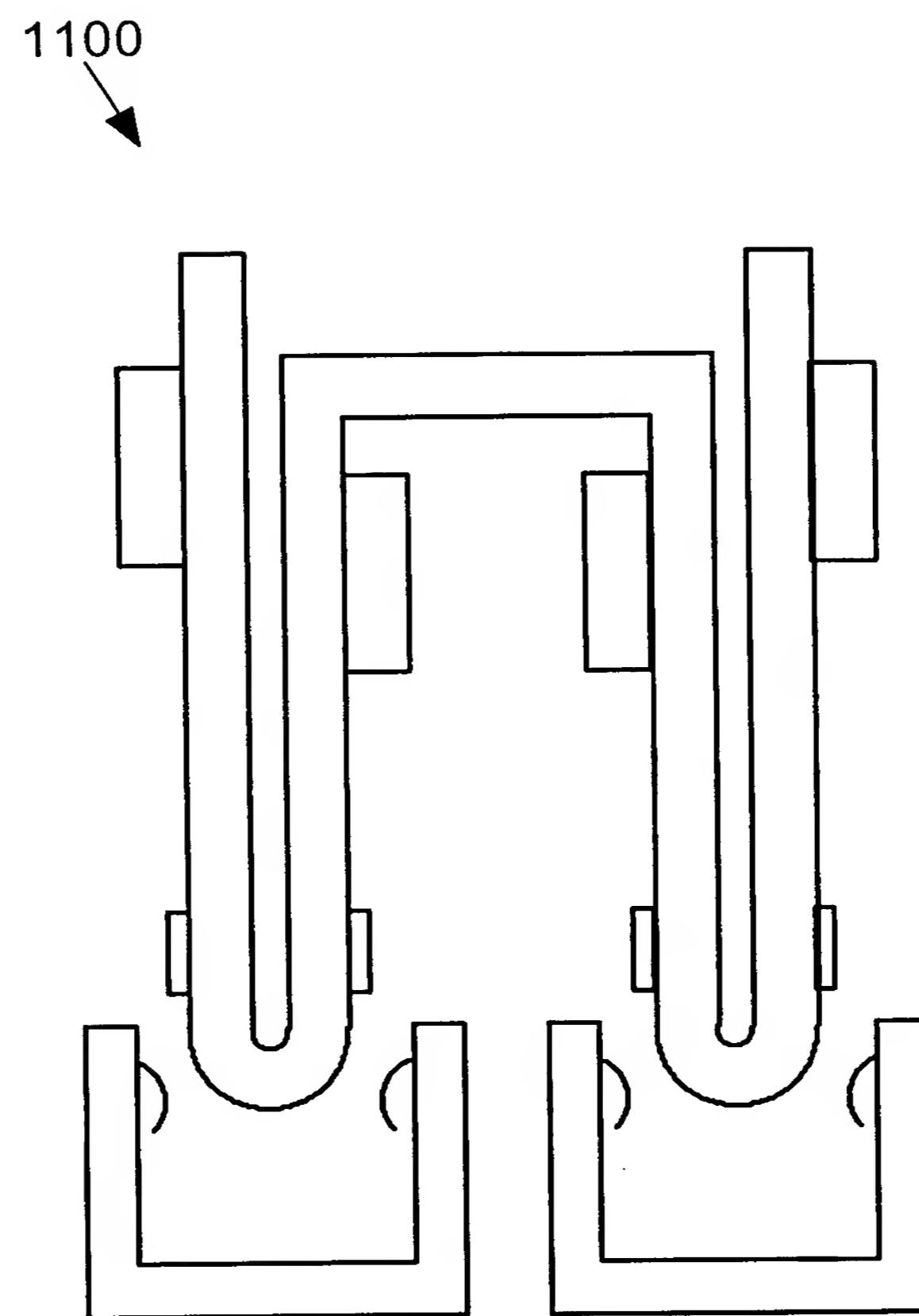


FIG. 11

1200

1204

1206

1208

1210

1212

1214

Providing a base layer

Applying an insulating
layer to first layer

Coating insulating layer

Etching traces onto the
insulating layerCoupling a semiconductor
to the insulating layerBending substrate through
180 degrees

Forming substrate

1202

FIG. 12